

# 3.3 V ECL Triple D Flip-Flop with Set and Reset

## MC100LVEL30

### Description

The MC100LVEL30 is a triple master-slave D flip-flop with differential outputs. Data enters the master latch when the clock input is LOW and transfers to the slave upon a positive transition on the clock input.

In addition to a common Set input individual Reset inputs are provided for each flip-flop. Both the Set and Reset inputs function asynchronous and overriding with respect to the clock inputs.

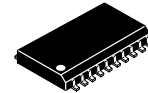
### Features

- 1200 MHz Minimum Toggle Frequency
- 450 ps Typical Propagation Delays
- ESD Protection: > 2 kV Human Body Model
- The 100 Series Contains Temperature Compensation.
- PECL Mode Operating Range:  
 $V_{CC} = 3.0\text{ V to }3.8\text{ V}$  with  $V_{EE} = 0\text{ V}$
- NECL Mode Operating Range:  
 $V_{CC} = 0\text{ V}$  with  $V_{EE} = -3.0\text{ V to }-3.8\text{ V}$
- Internal Input 75 k $\Omega$  Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-Free)  
(For Additional Information, see Application Note [AND8003/D](#))
- Flammability Rating: UL 94 V-0 @ 0.125 in,  
Oxygen Index: 28 to 34
- Transistor Count = 347 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



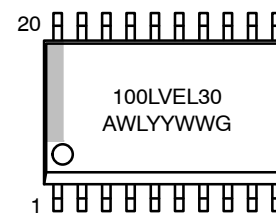
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SOIC-20 WB  
DW SUFFIX  
CASE 751D-05

### MARKING DIAGRAM\*



A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G = Pb-Free Package

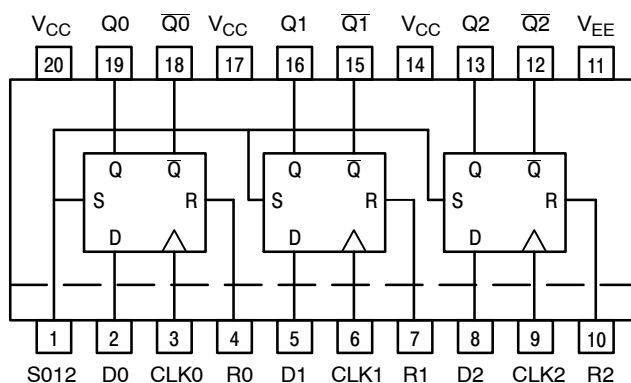
\*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

Device	Package	Shipping†
MC100LVEL30DWR2G	SOIC-20 WB (Pb-Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

# MC100LVEL30



Warning: All  $V_{CC}$  and  $V_{EE}$  pins must be externally connected to Power Supply to guarantee proper operation.

**Figure 1. Logic Diagram and Pinout: 20-Lead SOIC (Top View)**

**Table 2. PIN DESCRIPTION**

PIN	FUNCTION
D0–D2	ECL Data Inputs
R0–R2	ECL Reset Inputs
CLK0–CLK2	ECL Clock Inputs
S012	ECL Common Set Input
Q0–Q2; $\overline{Q0}$ – $\overline{Q2}$	ECL Differential Data Outputs
$V_{CC}$	Positive Supply
$V_{EE}$	Negative Supply

**Table 1. TRUTH TABLE**

R	S	D	CLK	Q	$\overline{Q}$
L	L	L	Z	L	H
L	L	H	Z	H	L
H	L	X	X	L	H
L	H	X	X	H	L
H	H	X	X	Undef	Undef

Z = LOW to HIGH Transition  
X = Don't Care

**Table 3. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
$V_{CC}$	PECL Mode Power Supply	$V_{EE} = 0\text{ V}$		8 to 0	V
$V_{EE}$	NECL Mode Power Supply	$V_{CC} = 0\text{ V}$		–8 to 0	V
$V_I$	PECL Mode Input Voltage NECL Mode Input Voltage	$V_{EE} = 0\text{ V}$ $V_{CC} = 0\text{ V}$	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 to 0 –6 to 0	V
$I_{out}$	Output Current	Continuous Surge		50 100	mA
$T_A$	Operating Temperature Range			–40 to +85	°C
$T_{stg}$	Storage Temperature Range			–65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC–20 WB SOIC–20 WB	90 60	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC–20 WB	30 to 35	°C/W
$T_{sol}$	Wave Solder	< 2 to 3 sec @ 248°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# MC100LEVEL30

**Table 4. LVPECL DC CHARACTERISTICS** ( $V_{CC} = 3.3\text{ V}$ ;  $V_{EE} = 0.0\text{ V}$  (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current		55	62		55	62		55	64	mA
$V_{OH}$	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
$V_{OL}$	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
$V_{IH}$	Input HIGH Voltage	2135		2420	2135		2420	2135		2420	mV
$V_{IL}$	Input LOW Voltage	1490		1825	1490		1825	1490		1825	mV
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .
2. Outputs are terminated through a  $50\ \Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

**Table 5. LVNECL DC CHARACTERISTICS** ( $V_{CC} = 0.0\text{ V}$ ;  $V_{EE} = -3.3\text{ V}$  (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current		55	62		55	62		55	64	mA
$V_{OH}$	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
$V_{OL}$	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
$V_{IH}$	Input HIGH Voltage	-1165		-880	-1165		-880	-1165		-880	mV
$V_{IL}$	Input LOW Voltage	-1810		-1475	-1810		-1475	-1810		-1475	mV
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .
2. Outputs are terminated through a  $50\ \Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

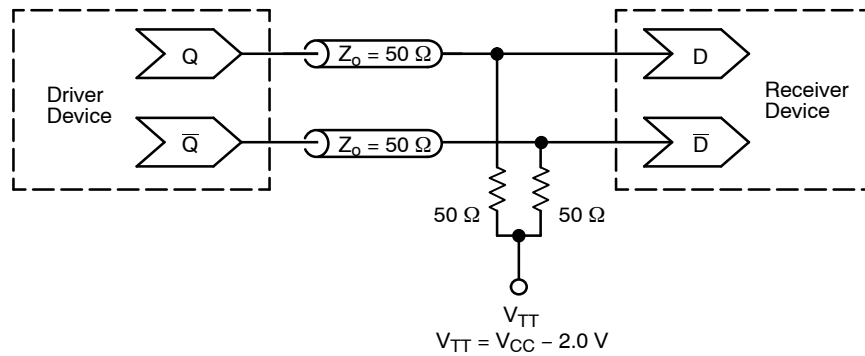
**Table 6. AC CHARACTERISTICS** ( $V_{CC} = 3.3\text{ V}$ ;  $V_{EE} = 0.0\text{ V}$  or  $V_{CC} = 0.0\text{ V}$ ;  $V_{EE} = -3.3\text{ V}$  (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\text{max}}$	Maximum Toggle Frequency	1.2			1.2			1.2			GHz
$t_{\text{PLH}}$ $t_{\text{PHL}}$	Propagation Delay to Output CLK, S, R	550		800	570		820	590		840	ps
$t_{\text{S}}$ $t_{\text{H}}$	Setup Time Hold Time	150 200	0 100		150 200	0 100		150 200	0 100		ps
$t_{\text{RR}}$	Set/Reset Recovery	400	200		400	200		400	200		ps
$t_{\text{PW}}$	Minimum Pulse Width CLK Set, Reset	400 650			400 650			400 650			ps
$t_{\text{JITTER}}$	Cycle-to-Cycle Jitter		9.5			10.5			10.8		ps
$t_{\text{r}}$ $t_{\text{f}}$	Output Rise/Fall Times Q (20%–80%)	280		550	280	450	550	280		550	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

1.  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .

## MC100LEVEL30



**Figure 2. Typical Termination for Output Driver and Device Evaluation**  
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices)

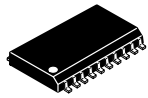
### Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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SCALE 1:1

SOIC-20 WB  
CASE 751D-05  
ISSUE H

DATE 22 APR 2015

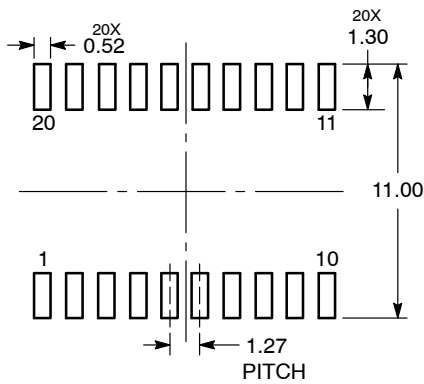


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

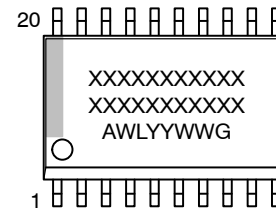
RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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